

## EAST Search History

| Ref # | Hits   | Search Query  | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|--------|---|---|------------------|---------|------------------|
| L1    | 400469 | (center middle) with (pad paddle bond bonding electrode terminal contact)                   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/03/16 17:51 |
| L2    | 70146  | (memory chip die dice multichip semiconductor ic (integrated adj circuit) component) same 1 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/03/16 17:52 |
| L3    | 40923  | (first second upper lower multi multiple plurality) same 2                                  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/03/16 17:53 |
| L4    | 8648   | (package packaging packaged module apparatus) same 3  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/03/16 17:53 |
| L5    | 2758   | 4 and ((exposing exposed expose opening) with (bondpad bond pad paddle electrode contact))  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/03/16 17:55 |
| L6    | 2269   | 5 and (metal pattern rearrange\$6 redistribut\$5 wiring wire)                               | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/03/16 18:22 |
| L7    | 2110   | (edge perimeter border end peripheral\$3) and 6   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/03/16 17:59 |
| L8    | 1621   | (insulating insulat\$6 resin epoxy encapsulat\$3 encase) and 7                              | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/03/16 18:23 |

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|     |      |   |   |    |     |                  |
|-----|------|---|---|----|-----|------------------|
| L9  | 2257 | 5 and (metal pattern rearrange\$6<br>redistribut\$5 trace iring wire) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2006/03/16 18:22 |
| L10 | 1735 | (insulating insulat\$6 resin epoxy<br>encapsulat\$3 encase) and 9     | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2006/03/16 18:39 |
| L11 | 2    | "6642627".PN.   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON  | 2006/03/16 18:39 |
| L12 | 1    | "4984050".PN.   | USPAT;<br>USOCR   | OR | OFF | 2006/03/16 19:35 |
| L13 | 1    | "5723822".PN.   | USPAT;<br>USOCR   | OR | OFF | 2006/03/16 19:35 |
| L14 | 1    | "5751065".PN.   | USPAT;<br>USOCR   | OR | OFF | 2006/03/16 19:35 |
| L15 | 1    | "6111317".PN.   | USPAT;<br>USOCR   | OR | OFF | 2006/03/16 19:35 |
| L16 | 1    | "6111317".PN.   | USPAT;<br>USOCR   | OR | OFF | 2006/03/16 19:36 |